Micron Technology, Inc.
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NAND MCP Silicon Improvement: Bond Pad Metallization Change

PCN: 33253

Published: 2019-06-25

Type: Manufacturing Process Change

Description: Micron will convert the NAND bond pad metallization from Ni/Pd to Aluminum (AI). Other DRAM/NAND technologies at Fab 6 use AI bond process and is proven to be more robust.

During the conversion period, customers will receive a mix of both bond pad types, however, the change will not impact the final packaged products. Micron has complete traceability via Lot ID number, Sales Order number, or Purchase Order number, etc. Full conversion to the new process is planned by January 2020. Micron reserves the right to ship either ALM2 or NiPd manufactured until the NiPd inventory has been depleted.

WAS	IS
Layers:	Layers:
Metal 2: Cu + Ni/Pd (Plating)	Metal 2: Al (Sputter)

Reason: Improved Product Quality and Reliability, Manufacturing Efficiency

Product Affected: NAND MCP (J4Q2, J4MK, J84F)

Affected Micron Part Number Component	Recommended Replacement	Customer Part Number
MT29AZ5A3CHHWD-18AAT.84F		
MT29AZ5A3CHHWD-18AIT.84F		**?**
MT29C1G12MAAIVAMD-5 IT		
MT29C1G12MAAJVAMD-5 IT		**557-1997-2-ND**
MT29C4G48MAYBBAKS-48 IT		
MT29C4G48MAYBBAMR-48 IT		**557-1998-2-ND**
MT29C4G48MAZBBAKB-48 IT		**557-1832-2-ND, ?**
MT29C4G48MAZBBAKS-48 IT		**557-1999-2-ND**
MT29RZ4B2DZZHHWD-18I.84F		**557-1889-2-ND**

*Materials that have been ordered are in **bold**.

Method of Identification: none

Micron Sites Affected: Fab 6 - US

Sample Available: 2019-07-31

Qual Data Available: 2019-07-31

Product Ship Date: 2020-01-31

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

Attachments

There are no attachments on this PCN